

An Analysis on a Pseudo-Differential Dynamic Comparator with Load Capacitance Calibration

Daehwa Paik, Masaya Miyahara, and <u>Akira Matsuzawa</u>

Tokyo Institute of Technology, Japan



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An Analyzed Comparator



• CLK_{Latch} becomes high

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- 1. Electric charge on the node Out_{int} flows into *gnd*
- 2. Current difference is determined by input signals
 - The difference is integrated on Out_{int} and becomes larger as time passes
- 3. The second stage regenerates the voltage difference

Fig. Transient waveform of a comparator [6], [7]. [6] M. Miyahara, et al., ASSCC, 2008 [7] D. Paik, et al., IEICE Trans. on Fundamentals, 2010 2011/10/27 D. Paik, Tokyo Tech.



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Analysis Conditions of a Pre-amplifier

- Process is 90-nm CMOS
- The size of all transistors is 2 $\mu m/100~nm$
- To simplify the analysis
 - The rising time of CLK_{Latch} to 1 ps
 - $-M_3$ and M_4 are in the deep triode when CLK_{Latch} is high
 - $V_{\text{out_int}}$ can be approximated as the drain voltage of M_1 (or M_2)



Fig. Simplified schematic of a dynamic amplifier when the CLK_{Latch} is high.

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Mismatch Contribution



Fig. Mismatch contribution (Remains are 2.4 %).

[2] V. Giannini, *et al.*, *ISSCC*, 2008 [3] G. Van der Plas, *et al.*, *ISSCC*, 2008

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 Mismatch is dominated by a pair of input transistors

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- Mismatch of the second stage is suppressed by the gain of the pre-amplifier
- *I*_{DS} is mainly decided by input transistors
 - Mismatch changes I_{DS} and the slew rate of Out_{int} is also varied

$$V_{\text{out_int}} = V_{\text{dd}} - \frac{I_{\text{DS}}}{C}t \longrightarrow \frac{dV_{\text{out_int}}}{dt} = -\frac{I_{\text{DS}}}{C}$$

- Load capacitance calibration
 [2], [3] is commonly used to
 compensate mismatch
 - To figure out the calibration effect, the gain is required



Channel-Length Modulation

- I_{DS} is affected by the channel-length modulation
 - $-\lambda$ is the channel-length coefficient

$$V_{\text{out_int}} = V_{\text{dd}} - \underbrace{I_{\text{DS}}}_{C} t \qquad I_{\text{DS}} = \frac{1}{2} \mu C_{\text{OX}} \frac{W}{L} V_{\text{eff}}^2 \left(1 + \lambda \left(V_{\text{DS}} - V_{\text{DS_sat}}\right)\right)$$



$$V_{\rm eff}$$
 $V_{\rm GS} - V_{\rm th}$

• V_{DS_sat} = the saturation condition of drain-source voltage (= V_{eff})

Fig. Influence of the channel-length modulation.



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Load Capacitance Calibration

- Using binary-weighted PMOS varactors
- By turning on or off PMOS, capacitance is varied
 Reduce offset voltage

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Input-Referred Compensated Voltage

Assumption

 Input signal of the second stage is decided when gain reaches its maximum

$$V_{\text{in_diff_cal}} = \left(\frac{dV_{\text{out_int}}}{dC}\right)_{\text{input-referred}} \times \Delta C_{\text{cal}}$$
$$= \left[-\frac{V_{\text{eff}}}{C} \times \left(1 + \frac{\lambda}{2} \left(V_{\text{dd}} - V_{\text{eff}}\right)\right) \times \left(N_{\text{Code}} - 2^{N_{\text{cal}} - 1}\right) \times \left(C_{\text{on}} - C_{\text{off}}\right)\right]$$

- $(N_{\text{Code}} 2^{N_{\text{Cal}-1}})$: ΔN_{Code} from the middle of calibration code N_{Code} : calibration code N_{Cal} : calibration resolution
- $(C_{on} C_{off})$: capacitance difference of a unit PMOS varactor C_{on} : on capacitance of a unit PMOS varactor C_{off} : off capacitance of a unit PMOS varactor

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Simulation Results

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- Simulation condition
 - 1 LSB = 1.5 mV
 - $-V_{dd} = 1.0$ V and $V_{in_com} = 0.5$ V
 - Size of a unit varactor is W/L = 600 nm/100 nm



Fig. Input-referred compensated voltage by the capacitance calibration.



PVT Variation

- If surrounding condition is varied after compensation, calibration accuracy is degraded
 - Process is fixed in the factory
 - Voltage and Temperature should be considered
- Assumption
 - An error due to PVT variation, σ_{V_PVT} , is **uncorrelated** with offset after calibration, $\sigma_{V_offset0}$

$$\sigma_{V_offset}^2 = \sigma_{V_offset0}^2 + \sigma_{V_PVT}^2$$

 $(\sigma_{V_{offset0}} \text{ is extracted from simulation data})$

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Input Common-Mode Voltage

- Input common-mode voltage is fluctuated
- Standard deviation of calibration code is σ_{Code}

Error due to
$$V_{\text{eff}} = \frac{\partial V_{\text{in_diff_cal}}}{\partial V_{\text{in_com}}} \times \Delta V_{\text{in_com}}$$

$$= \frac{\Delta V_{\text{eff}}}{C} \left(1 + \frac{\lambda}{2} \left(V_{\text{dd}} - V_{\text{eff}} \right) \right) \times \left(C_{\text{on}} - C_{\text{off}} \right) \sigma_{\text{Code}}$$

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Error due to
$$\lambda = \frac{V_{\text{eff}}}{C} \times (V_{\text{dd}} - V_{\text{eff}}) \frac{\Delta \lambda}{2} \times (C_{\text{on}} - C_{\text{off}}) \sigma_{\text{Code}}$$

Error due to
$$(V_{dd} - V_{eff}) = -\frac{V_{eff}}{C} \times \frac{\lambda}{2} \Delta V_{eff} \times (C_{on} - C_{off}) \sigma_{Code}$$

$$\sigma_{V_PVT_VCOM} = \frac{V_{eff}}{C} \left(1 + \frac{\lambda}{2} \left(V_{dd} - V_{eff} \right) \right) \\ \times \sqrt{\left[\frac{\Delta V_{eff}}{V_{eff}} - \frac{\lambda \Delta V_{eff}}{2 + \lambda \left(V_{dd} - V_{eff} \right)} \right]^2} + \left(\frac{\left(V_{dd} - V_{eff} \right) \Delta \lambda}{2 + \lambda \left(V_{dd} - V_{eff} \right)} \right)^2} \times \left(C_{on} - C_{off} \right) \sigma_{Code}$$

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Simulation Results 12 ΓΟΚΥΟ **Pursuing Excellence** Calibration is conducted when V_{dd} is 1.0 V, V_{in_com} is 0.5 V, and *Temp* is 27 °C Simulation results — Estimation — SNDR decrease 4 0 SNDR decrease [dB] 3 σ_{V_offset} [mV] SNDR decrease = SNDR - SQNR $= -10 \log \left(1 + \frac{12}{V^2} \sigma_V^2 \right)$ 0 8 440 560 460 520 480 500 540 Input common-mode voltage after calibration [mV]

Fig. Influence of input common-mode voltage on the capacitance calibration (1 LSB = 4.5 mV and a number of the Monte Carlo simulation is 500).



Influence of Supply Voltage 13 ΓΟΚ • Calibration is conducted when V_{dd} is 1.0 V, V_{in_com} is 0.5 V, and *Temp* is 27 °C Simulation results — Estimation — SNDR decrease $\sigma_{V_PVT_Vdd} = \frac{V_{eff}}{C} \times \left(1 + \frac{\lambda}{2} \left(V_{dd} - V_{eff}\right)\right)$ 0.8 0 - 0.2 0 .6



Fig. Influence of supply voltage on the capacitance calibration (1 LSB = 4.5 mV and a number of the Monte Carlo simulation is 500).



Influence of Temperature

• Calibration is conducted when V_{dd} is 1.0 V, V_{in_com} is 0.5 V, and *Temp* is 27 °C

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Temperature after calibration [°C]

Fig. Influence of temperature on the capacitance calibration (1 LSB = 4.5 mV and a number of the Monte Carlo simulation is 500).

Conclusions

- A pseudo-differential dynamic comparator with load capacitance calibration is analyzed
 - The gain of a dynamic amplifier
 - Expressed by a ratio of V_{dd} to V_{eff} and λ of an input transistor
 - Gain is inversely proportional to $V_{\rm eff}$
 - Thermal noise, input-referred compensate voltage, and influence of PVT variation are analyzed
 - A dynamic comparator is sensitive to PVT variation
 - Mainly decided by $V_{\rm eff}$



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